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TECHNICAL REPORT

EMC IC modelling -
Part 4-1: Use of ICIM-CI model to predict the IC conducted immunity in a PCB

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EMC IC modelling - Part 4-1: Use of ICIM-CI model to predict the IC conducted immunity in a PCB

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The language used for the development of this Technical Report is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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1 Scope

This part of IEC 62433-4 provides an overview of good practices to extract an ICIM-CI model from measurements and to build a numerical model of the PCB in which the ICIM-CI model is used to predict RF immunity of an IC in its application PCB.

This document also discusses factors which can be considered to obtain proper results in an ICIM-CI model extraction and use of the actual model at the PCB level.

2 Normative references

There are no normative references in this document.